

AMENDMENTS TO THE DRAWINGS

In response to the drawing objection, a replacement sheet of Fig. 3 is submitted herewith to show the feature of “a light-emitting diode comprising a flip-chip-type gallium nitride compound semiconductor light-emitting device”.

Please cancel current Figure 3 and replace with the attached replacement drawing sheet. In particular, element 4 of Figure 3 is a wire.

Attachment:

- One (1) Annotated Sheet (Fig. 3)
- One (1) Replacement Sheet (Fig. 3)

REMARKS

Claims 1, 4-9 and 12 are all the claims pending in the application. Claims 1 and 9 have been amended by this Amendment.

Independent claims 1 and 9 have been amended to for clarity. Independent claims 1 and 9 have been amended to recite that the bonding pad layer is provided atop a portion of the ohmic electrode layer, wherein said portion is less than the entirety of the ohmic electrode layer, and wherein the adhesion layer has the same dimension as the bonding pad layer, respectively.

No new matter has been added. Entry of the Amendment is respectfully requested.

I. Specification and Drawing Objection

The Examiner objected to the Amendment filed on August 28, 2008 as introducing new matter into the specification. In particular, the Examiner asserted that the element 4 gold wire in Figure 3 for connecting the submount and the TO-18 stem is not supported by the original disclosure.

Without acquiescence in the merits of the above objection, and to advance prosecution, Applicants submit herewith a replacement drawing Fig. 3 to show the feature of “a light-emitting diode comprising a flip-chip-type gallium nitride compound semiconductor light-emitting device”. In particular, element 4 of Figure 3 is a wire (rather than a gold wire). No new matter has been added.

The Example of the present specification describes fabrication of a flip-chip-type device and lamp comprising the same, including an Au bonding pad, device chip flip-chip-mounted on a submount, and mounting the resultant product on a TO-18 stem by wiring (page 13, lines 33-37 of the specification).

Withdrawal of the objection to the specification and acceptance of the replacement sheet of Fig. 3 are respectfully requested.

II. Response to Claim Rejection under 35 U.S.C. § 103 Over Kamimura

Claims 1, 4-9 and 12 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Kamimura et al. (JP 2002368271 A; “Kamimura”).

Applicants respectfully traverse this rejection.

Independent claims 1 and 9 presently recite that the bonding pad layer is provided atop a portion of the ohmic electrode layer, wherein said portion is less than the entirety of the ohmic electrode layer, and that the adhesion layer has the same dimension as the bonding pad layer.

In contrast, Figure 1 of Kamimura clearly shows that the whole surface of p-electrode (18) is covered by the p-side electrode film (20). Kamimura discloses that the p-side electrode film is preferably formed over the whole surface of the positive electrode. Paragraph [0009]. Further, Kamimura discloses that it is desirable to make the configuration of n-lateral electrode film the same as that of the configuration of p-lateral electrode film. Paragraph [0015].

Applicants submit herewith a partial translation of the relevant sections of Kamimura for the Examiner’s review and consideration.

Moreover, there is no apparent reason which would lead one of ordinary skill to form bonding pad layer (upper layer) 20b of Kamimura on anything less than the entirety of the underlying ohmic electrode layer.

Accordingly, it is respectfully submitted that the present claims are patentable over Kamimura, and withdrawal of the foregoing rejection under 35 U.S.C. § 103 is requested.

III. Conclusion

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,

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23373

CUSTOMER NUMBER

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Date: January 27, 2009

1 Flip-Clip-Type Light-Emitting Device

2 Air Bump

3 Submount

4 Air-Wire Wire

5 TD-18 Stem

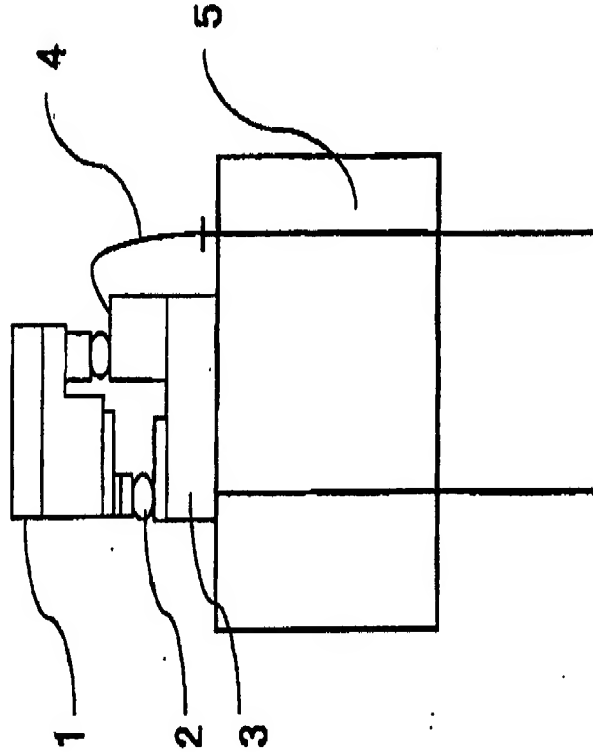


Fig. 3